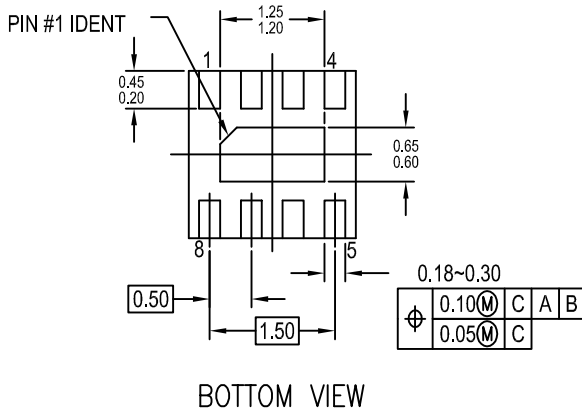
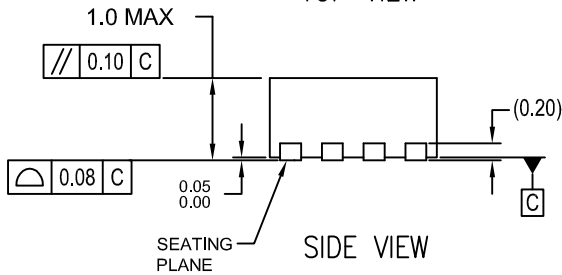
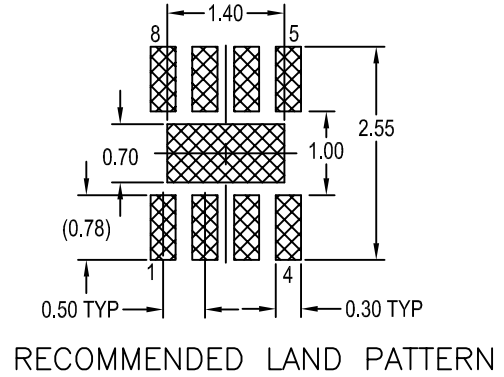
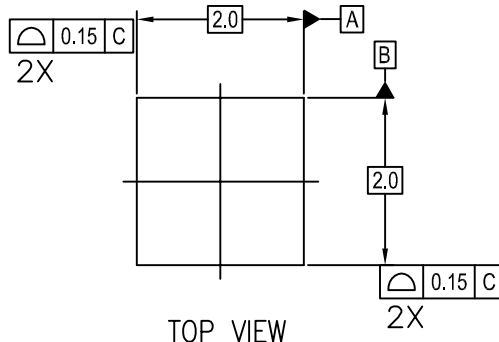


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REVISIONS				
LTR	DESCRIPTION	EDCN	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL		30-5-2002	FEITAN
B	UPDATE LAND PATTERN DIMS.	ECH-MKT-MLP08CrevB	19-5-2003	FEITAN



NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-229, VARIATION VCCD-3, DATED 11/2001
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994

MLP08CrevB

APPROVALS	DATE	FAIRCHILD SEMICONDUCTOR			
DRAWN FEITAN	29-5-2002	Bayan Lepas, FIZ, 11900, Penang, Malaysia.			
DFTG. CHK.		8LD,MLP DUAL,JEDEC MO-229, 2MM SQUARE			
ENGR. CHK.					
		SCALE N/A	SIZE N/A	DRAWING NUMBER MKT-MLP08C	REV B
		DO NOT SCALE DRAWING		SHEET 1 of 1	